

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Unknown
Serial No.:	Unknown	Group Art Unit:	Unknown
Filed:	Herewith	Docket:	303.685US2
Title:	MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION		

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

Pursuant to 37 C.F.R. §1.98(d), copies of some of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 09/584157, filed on May 31, 2000, which is relied upon for an earlier filing date under 35 U.S.C. §120.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :Unknown

Filing Date: Herewith

Title: MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION

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Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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24 Nov '03

By



Timothy B. Clise

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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Applicant Number	Unknown
	Filing Date	Even Date Herewith
	First Named Inventor	Ahn, Kie
	Group Art Unit	Unknown
	Examiner Name	Unknown
Sheet 1 of 9		Attorney Docket No: 303.685US2

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2001/0002333	05/31/2001	Huang, Chao-Yuan , et al.	438	637	03/29/1999
	US-1,254,987	01/29/1918	Cooper, H. S.			10/15/1917
	US-1,976,375	10/09/1934	Smith, J. K.	148	11.5	01/27/1931
	US-2001/0054771	12/27/2001	Wark, J. M., et al.			
	US-2002/0014646	02/07/2002	Tsu, et al.	257	296	
	US-2002/0028552	03/07/2002	Lee, et al.	438	243	
	US-2002/0096768	07/25/2002	Joshi, Rajiv Vasant	257	750	
	US-2002/0109233	08/15/2002	Farrar, Paul A.	257	762	
	US-2,244,608	06/03/1941	Cooper, H. S.	75	138	02/09/1939
	US-2,842,438	07/08/1958	Saarivirta, M. J., et al.	75	153	08/02/1956
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	US-3,923,500	12/02/1975	Kitazawa, Kunio , et al.	75	156.5	09/04/1974
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	US-4,022,931	05/10/1977	Black, J. , et al.	427	91	06/13/1975
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	US-4,158,719	06/19/1979	Frantz, E.	428	567	06/09/1977
	US-4,233,066	11/11/1980	Sundin, Anders O., et al.	75	142	08/14/1975
	US-4,314,594	02/09/1982	Pfeifer, Friedrich , et al.	148	108	04/29/1980
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	US-4,389,429	06/21/1983	Soclof, Sidney I.	438	492	06/28/1982

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Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached

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PTO/SB08A(10-01)
Approved for use through 10/31/2002, OMB 851-0031
US Patent & Trademark Office, U.S. DEPARTMENT OF COMMERCE

Complete if Known

Application Number	Unknown
Filing Date	Even Date Herewith
First Named Inventor	Ahn, Kie
Group Art Unit	Unknown
Examiner Name	Unknown

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	US-4,962,058	10/09/1990	Cronin, J. E., et al.	437	187	04/14/1989
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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Complete if Known

Applicant Number	Unknown
Filing Date	Even Date Herewith
First Named Inventor	Ahn, Kie
Group Art Unit	Unknown
Examiner Name	Unknown

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Attorney Docket No: 303.685US2

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	US-5,578,146	11/26/1996	Grant, L. A., et al.	148	437	01/16/1996
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	US-5,635,253	06/03/1997	Canaperi, , et al.	427	437	06/07/1995
	US-5,654,245	08/05/1997	Allen, Gregory L.	438	629	03/23/1993
	US-5,667,600	09/16/1997	Grensing, Fritz C., et al.	148	437	03/31/1994
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	US-5,679,608	10/21/1997	Cheung, , et al.	437	195	06/05/1995
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	US-5,695,810	12/09/1997	Dubin, , et al.	427	96	11/20/1996
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	US-5,719,410	02/17/1998	Suehiro, S., et al.	257	77	12/16/1996
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	US-5,852,871	12/29/1998	Khandros, I. Y.	29	843	12/11/1995

EXAMINER

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Substitute Disclosure Statement Form (PTO-1449)

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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Application Number	Unknown
	Filing Date	Even Date Herewith
	First Named Inventor	Ahn, Kie
	Group Art Unit	Unknown
	Examiner Name	Unknown
Sheet 4 of 9		Attorney Docket No: 303.685US2

	US-5,858,877	01/12/1999	Dennison, C. H., et al.	438	700	01/21/1997
	US-5,891,797	04/06/1999	Farrar, P. A.	438	619	10/20/1997
	US-5,891,804	04/06/1999	Havemann, R. H., et al.	438	674	04/14/1997
	US-5,895,740	04/20/1999	Chien, Rong-Wu , et al.	430	313	11/13/1996
	US-5,897,370	04/27/1999	Joshi, R. V., et al.	438	632	10/28/1996
	US-5,907,772	05/25/1999	Iwasaki, Haruo	438	253	02/26/1997
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	US-5,925,930	07/20/1999	Farnworth, Warren M., et al.	257	737	05/21/1996
	US-5,930,669	07/27/1999	Uzoh, Cyprian	438	627	04/03/1997
	US-5,932,928	08/03/1999	Clampitt, D. A.	257	758	07/03/1997
	US-5,940,733	08/17/1999	Beinglass, Israel , et al.	438	655	07/29/1997
	US-5,948,467	09/07/1999	Nguyen, T. , et al.	427	99	07/24/1998
	US-5,962,923	10/05/1999	Xu, Z. , et al.	257	774	08/07/1995
	US-5,972,179	10/26/1999	Chittipeddi, , et al.	204	192.17	09/30/1997
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	US-5,976,710	11/02/1999	Sachdev, K. G. , et al.	428	620	04/10/1997
	US-5,981,350	11/09/1999	Geusic, J. E., et al.	438	386	05/29/1998
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	US-5,989,623	11/23/1999	Chen, Liang-Yuh , et al.	427	97	08/19/1997
	US-5,994,777	11/30/1999	Farrar, P. A.	257	758	08/26/1998
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EXAMINER

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Applicati n Number Unknown

Filing Date Even Date Herewith

First Named Inventor Ahn, Kie

Gr up Art Unit Unknown

Examiner Name Unknown

Sheet 5 of 9

Attorney Docket No: 303.685US2

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	US-6,139,699	10/31/2000	Chiang, T. , et al.	204	192.15	05/27/1997
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	US-6,207,222	03/27/2001	Chen, Liang-Yuh , et al.	427	97	08/24/1999
	US-6,207,553	05/27/2001	Buynoski, M. , et al.	438	622	01/26/1999
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	US-6,208,016	03/27/2001	Farrar, Paul	257	643	02/24/1999
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	US-6,249,056	06/19/2001	Kwon, Dong-chul , et al.	257	758	11/01/1999
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	First Named Inventor	Ahn, Kie
	Group Art Unit	Unknown
	Examiner Name	Unknown
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	Group Art Unit	Unknown
	Examiner Name	Unknown
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